

Change(s) applied

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/M.W.J./

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material because the active layer-bearing substrate is attached to the support material. This attachment can be achieved e.g. by screwing, riveting and preferably spot-welding. In Figure ~~3~~¹ the crosses (3) therefore represent e.g. spot welds.

A particular advantage of the anode according to the invention is that the shielding caused by the bubbles forming at the anode in operation and the resulting inhomogeneity of the deposition at the cathode can be essentially compensated for, so that layers which have a more uniform thickness can be deposited at the cathode. A person skilled in the art will be able to determine, by carrying out simple preliminary tests, which geometrical arrangement is to be chosen in the individual case.

This anode can, according to the invention, likewise be connected as a cathode.

Furthermore the invention relates to electroplating processes in which an anode as described above is used.

The use of an anode used as described above for electroplating is a further subject of the invention.

The invention is described in more detail below by means of examples.

Examples:

Example 1:

Additive degradation was investigated under the working conditions of a sulfuric acid copperplating bath in d.c. operation. A sulfur compound served as additive. Two d.c. plates with an active layer of mixed oxide were used as anodes. The first consisted only of the anode base and the second